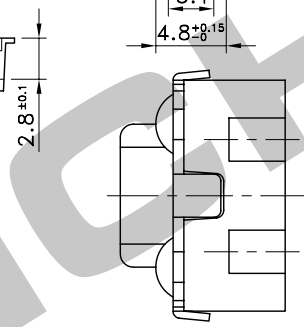
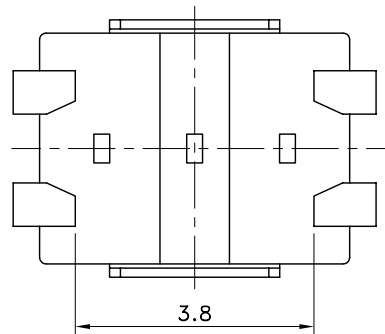


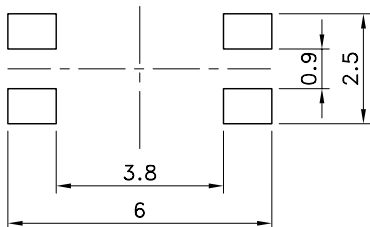
P.C.B TERMINAL POSITION



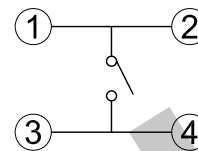
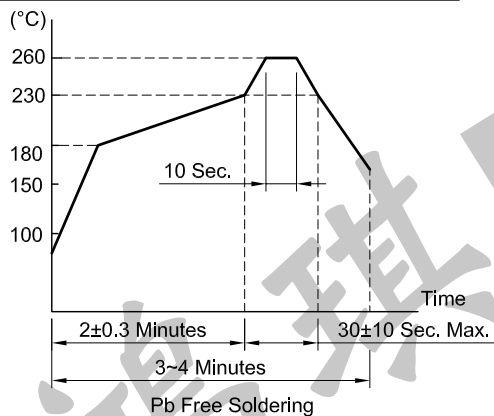
VIEW A



CIRCUIT ARRANGEMENT



REFLOW SOLDERING CONDITIONS



SPECIFICATIONS

- 1. Rating : DC 12V 50mA
- 2. Contact Resistance : 100mΩ Max.
- 3. Insulation Resistance : 100MΩ Min. at DC 100V
- 4. Dielectric strength : AC 250V for 1 Minute
- 5. Operating Force : 160±50gf
- 6. Stroke : 0.2±0.1mm
- 7. Life : 50,000 Cycles
- 8. Taping package : 3,000 Pcs/Reel
- 9. Operation Temperature Range : -40~+125°C
- 10. Storage Temperature Range : -40~+90°C
- 11. Reflow soldering : According Reflow Profile Max. 2 Times

| | | | |
|-----------|-------|-----------|-------|
| REVISION: | DATE: | REVISION: | DATE: |
|-----------|-------|-----------|-------|

| | | | |
|---------|-------------------------------|-----------------------------------|--------------------|
| UNIT:mm | THIRD ANGLE PROJECTION METHOD | TOL. UNLESS OTHERWISE STATED:±0.3 | CODE NO.:HCH-860-7 |
|---------|-------------------------------|-----------------------------------|--------------------|

| | | | |
|------------|------------|--|------------------|
| ISSUED | CONFIRMED | HCH ISO9001 Certified ISO14001 Certified HORNG CHIH 鴻琪股份有限公司 | PART NO. |
| John | Elvis | | STS-090-A |
| 2012.06.01 | 2012.06.01 | | |